

ABSTRACT

A heat treatment apparatus (100) having: a susceptor (2) rotatably provided in a heat treatment vessel (1), on which a wafer (W) is placed; a preheat ring (3) surrounding a periphery of the susceptor (2) to be close to and in non-contact with the susceptor, which is supported by a base (4) provided in the heat treatment vessel (1); and a heating apparatus (8) for heating a wafer (W) placed on the susceptor (2), wherein the preheat ring (3) is formed such that an inner peripheral center (31a) is eccentric to an outer periphery (32). The preheat ring (3) is moved around the susceptor (2); the preheat ring (3) is positioned to minimize a distance between the inner peripheral center (31a) of the preheat ring (3) and the center (2b) of the susceptor (2); and thereafter a heat treatment is performed to a wafer (W).